ASSOCIATION CONNECTIN	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ. Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				Materials ar	ials and Mfg Information				
Supplier Inforn	nation														
Company name*		Company unique ID			ı	Unique ID Authority				Res	Response Date*				
nsemi										202	2025-06-04				
Contact Name		Title - Contact]	Phone - Contact*				Em	Email - Contact*				
Product-Env-Stewa	ards		Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative]	Phone - Representative*				Em	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Pre	Product-Env-Stewards@onsemi.com			
Requesto	er Item Number			Mfr Item Name			Effective Dat	e Versi	on	Manufacturing Site		Weight*	UOM	Unit Type	
				Integrated Driver	er & MOSFET		2025-06-04 PH		РНА		98.45	mg	Each		
Ianufacturing	Proccess Information	on													
Terminal Plating / Grid Array Material		rial To	Terminal Base Alloy J-STD-		J-STD-020 M	SL Rating	Peak Process Body Temper		y Temperatu	ture Max Time at Peak Temper		perature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		C	CU Alloy 3		3		260		C	30	s	seconds 3			
omments															
TTENTION: MSI	3 Rated item requires I	Bake and D	ry Pack (after	r electrical test)											
or more informati	on regarding material co	mposition p	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.0	mg	Supplier	Silicon (Si)	7440-21-3		8	mg
Die Attach Solder	12.0	mg	Supplier	Silver (Ag)	7440-22-4		0.3	mg
			A	Lead (Pb)	7439-92-1	7a	11.1	mg
			Supplier	Tin (Sn)	7440-31-5		0.6	mg
Lead Frame	50.35	mg	Supplier	Silver (Ag)	7440-22-4		1.3594	mg
			Supplier	Tin (Sn)	7440-31-5		0.1208	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0957	mg
			Supplier	Chromium (Cr)	7440-47-3		0.146	mg
			Supplier	Copper (Cu)	7440-50-8		48.628	mg
Mold Compound-Black	26.0	mg		Epoxy resin	proprietary data		1.222	mg
			Supplier	Phenol Resin	Proprietary Data		1.222	mg
			Supplier	Carbon Black (C)	1333-86-4		0.026	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		23.53	mg
Plating	1.8	mg	Supplier	Tin (Sn)	7440-31-5		1.8	mg
Wire Bond	0.3	mg	Supplier	Palladium (Pd)	7440-05-3		0.003	mg
			Supplier	Copper (Cu)	7440-50-8		0.297	mg